

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Cheng-Ta Ko</td> <td>02/16/2009</td> </tr> <tr> <td>Min-Lin Lee</td> <td>02/16/2009</td> </tr> <tr> <td>Wei-Chung Lo</td> <td>02/18/2009</td> </tr> <tr> <td>Shur-Fen Liu</td> <td>03/06/2009</td> </tr> <tr> <td>Jinn-Shing King</td> <td>03/09/2009</td> </tr> <tr> <td>Shinn-Juh Lai</td> <td>02/18/2009</td> </tr> <tr> <td>Yu-Hua Chen</td> <td>02/16/2009</td> </tr> </tbody> </table>		Name	Execution Date	Cheng-Ta Ko	02/16/2009	Min-Lin Lee	02/16/2009	Wei-Chung Lo	02/18/2009	Shur-Fen Liu	03/06/2009	Jinn-Shing King	03/09/2009	Shinn-Juh Lai	02/18/2009	Yu-Hua Chen	02/16/2009
Name	Execution Date																
Cheng-Ta Ko	02/16/2009																
Min-Lin Lee	02/16/2009																
Wei-Chung Lo	02/18/2009																
Shur-Fen Liu	03/06/2009																
Jinn-Shing King	03/09/2009																
Shinn-Juh Lai	02/18/2009																
Yu-Hua Chen	02/16/2009																
RECEIVING PARTY DATA																	
Name:	Industrial Technology Research Institute																
Street Address:	No. 195, Sec. 4, Chung Hsing Rd., Chutung,																
City:	Hsinchu																
State/Country:	TAIWAN																
Postal Code:	31040																
PROPERTY NUMBERS Total: 1																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12468058</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12468058												
Property Type	Number																
Application Number:	12468058																
CORRESPONDENCE DATA																	
Fax Number:	(949)660-0809																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
Email:	Usa@cipgroup.com.tw																
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE																
Address Line 1:	7F.-1, NO.100, ROOSEVELT RD., SEC. 2,																
Address Line 4:	Taipei, TAIWAN 100																
ATTORNEY DOCKET NUMBER:	29834-US-PA																
NAME OF SUBMITTER:	Belinda Lee																

CH \$40.00 12468058

500874001

PATENT
REEL: 022762 FRAME: 0757

Total Attachments: 2

source=29834-Assignment#page1.tif

source=29834-Assignment#page2.tif

ASSIGNMENT

WHEREAS,

- | | |
|---------------------|-------------------|
| 1. Ko, Cheng-Ta | 2. Lee, Min-Lin |
| 3. Lo, Wei-Chung | 4. Liu, Shur-Fen |
| 5. King, Jinn-Shing | 6. Lai, Shinn-Juh |
| 7. Chen, Yu-Hua | |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **STRUCTURE OF MULTIPLE COAXIAL LEADS WITHIN SINGLE VIA IN SUBSTRATE AND MANUFACTURING METHOD THEREOF**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ko, Cheng-Ta
Sole or First Joint Inventor: Ko, Cheng-Ta

Date: 2009/2/16

Signature: Lee Min-Lin
Second Joint Inventor (if any): Lee, Min-Lin

Date: 2009/2/16

Signature: Wei-Chung Lo
Third Joint Inventor (if any): Lo, Wei-Chung

Date: 2/18/2009

Signature: Shur-Fen Liu
Fourth Joint Inventor (if any): Liu, Shur-Fen

Date: 2009. 3. 6

Signature: King Jinn-Shing
Fifth Joint Inventor (if any): King, Jinn-Shing

Date: 2009. 3. 9

Signature: Shinn-Juh Lai
Sixth Joint Inventor (if any): Lai, Shinn-Juh

Date: 2009. 02. 18

Signature: Chen, Yu-Hua
Seventh Joint Inventor (if any): Chen, Yu-Hua

Date: 2009/2/16